

## REMARKS

Claims 1 – 13 are pending and rejected.

The applicants' attorney cancels claim 13 and amends claims 1 and 12. The applicants' attorney respectfully disagrees with the examiner's rejection of claims 1 – 12 and asserts that these claims, as amended, are in condition for allowance for the reasons discussed below.

### **Rejection of claims 1 – 11 under 35 U.S.C. §103(a)**

The applicants' attorney respectfully disagrees with the examiner's rejection of claim 1 in view of U.S. Patent 6,285,067 issued to Hyoudo *et. al.* (Hyoudo) because Hyoudo fails to disclose forming a pad on a second wafer wherein the pad projects from a surface of the second wafer.

The applicants' claim 1, as amended, recites forming a pad on a second wafer, the pad projecting from a surface of the second wafer.

For example, as shown in FIGS. 3D and 3E, and discussed in paragraphs 20 – 22 of the specification, a wafer-level package (shown but not labeled with a reference number) includes a cap wafer 203 having a gasket 201, and a base wafer 207 having a surface (also shown but not labeled with a reference number). The wafer-level package also includes a mating pad 305 that projects from the surface of the base wafer 207, and that has a surface (also shown but not labeled with a reference number) for bonding with the gasket 201 to form a hermetically sealed environment 211 (FIG. 3E). The pad 305 improves the bondability of the gasket 201 with the base wafer 207.

In contrast, Hyoudo fails to disclose forming a pad on a second wafer wherein the pad projects from a surface of the second wafer. Hyoudo discloses an electronic device (shown in FIGS. 4A and 4B but not labeled with a reference number) that includes a substrate 21 having an element mounting section 50 for mounting electronic components, and a cover member 31a fixed to the substrate 21. The substrate 21

includes a main surface 22a (not shown in FIGS. 4A and 4B, but discussed in Col. 3, lines 29 – 35 in conjunction with FIG. 4A, and shown in FIG. 2A) on which the mounting section 50 is located. The cover member 31a includes a depression 24 that corresponds to the mounting section 50 such that when the member 31a is fixed to the substrate 21, a hermetically sealed compartment is formed to protect the electronic component mounted on the substrate 21. The substrate 21 does not include a pad projecting from the main surface 22a of the substrate 21. Therefore, unlike the applicants' claimed wafer-level package, Hyoudo's electronic device does not include a pad projecting from the main surface 22a.

Claims 2 – 11 are patentable by virtue of their dependencies from claim 1.

#### **Rejection of Claim 12 under 35 U.S.C. §102(e)**

Claim 12, as amended, is patentable over Hyoudo for reasons similar to those recited in support of claim 1 over Hyoudo.

#### **Conclusion**

The applicants' attorney respectfully requests that the examiner withdraw the rejection of claims 1 – 12 in view of the amendments and remarks, and issue an allowance for these claims.

Should any additional fees be required, please charge them to Deposit Account No. 07-1897.

If the examiner believes that a phone interview would be helpful, he is respectfully requested to contact the Applicants' attorney, John Janeway, at (425) 455-5575.

DATED this 13th day of May, 2005.

Respectfully submitted,  
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